

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

MSISH101DN-T1-GE3

Product specification

Description

The MSISH101DN-T1-GE3 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

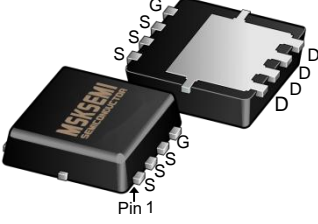
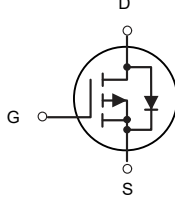

Features

- $V_{DS} = -30V$ $I_D = -70A$
- $R_{DS(ON)} < 9.3m\Omega$ @ $V_{GS} = -10V$

Application

- Battery protection
- Load switch
- Uninterruptible power supply

Reference News

DFN3X3-8L	P-Channel MOSFET	Marking
		

Absolute Maximum Ratings ($T_c = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	-70	A
$I_D @ T_c = 75^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	-35	A
IDM	Pulsed Drain Current ²	-175	A
EAS	Single Pulse Avalanche Energy ³	31	mJ
$P_D @ T_c = 25^\circ C$	Total Power Dissipation ⁴	31.2	W
TSTG	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	4	$^\circ C/W$

Electrical Characteristics ($T_J=25^\circ\text{C}$, nless otherwise specified)

Parameter		Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics							
Drain-Source Breakdown Voltage		V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-30	-	-	V
Gate-body Leakage current		I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	T _J =25℃	I _{DSS}	V _{DS} = -24V, V _{GS} = 0V	-	-	-1	μA
	T _J =55℃			-	-	-5	
Gate-Threshold Voltage		V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-1.0	-1.6	-2.5	V
Drain-Source On-Resistance ²		R _{DS(on)}	V _{GS} = -10V, I _D = -12A	-	6.5	9.3	mΩ
			V _{GS} = -4.5V, I _D = -8A	-	9.5	14.5	
Forward Transconductance		g _{fs}	V _{DS} = -5V, I _D = -20A	-	28	-	S
Dynamic Characteristics							
Input Capacitance		C _{iss}	V _{DS} = -15V, V _{GS} =0V, f =1MHz	-	4320	-	pF
Output Capacitance		C _{oss}		-	529	-	
Reverse Transfer Capacitance		C _{rss}		-	487	-	
Switching Characteristics							
Gate Resistance		R _g	V _{DS} = 0V, V _{GS} = 0V, f=1.0MHz	-	4.0	-	Ω
Total Gate Charge		Q _g	V _{GS} = -10V, V _{DS} = -15V, I _D = -15A	-	45	-	nC
Gate-Source Charge		Q _{gs}		-	8.5	-	
Gate-Drain Charge		Q _{gd}		-	12.8	-	
Turn-On Delay Time		t _{d(on)}	V _{GS} = -10V, V _{DD} = -15V, R _G = 2.5Ω, I _D = -15A	-	18.9	-	nS
Rise Time		t _r		-	15.7	-	
Turn-Off Delay Time		t _{d(off)}		-	64.8	-	
Fall Time		t _f		-	36.5	-	
Drain-Source Body Diode Characteristics							
Diode Forward Voltage ²		V _{SD}	I _S = -1A, V _{GS} = 0V	-	-	-1	V
Continuous Source Current ^{1,5}		I _S	V _G =V _D =0V , Force Current	-	-	-65	A

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{DD} = -25V, V_{GS} = -10V, L = 0.1mH, I_{AS} = -25A$
- 4.The power dissipation is limited by 150 $^\circ\text{C}$ junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

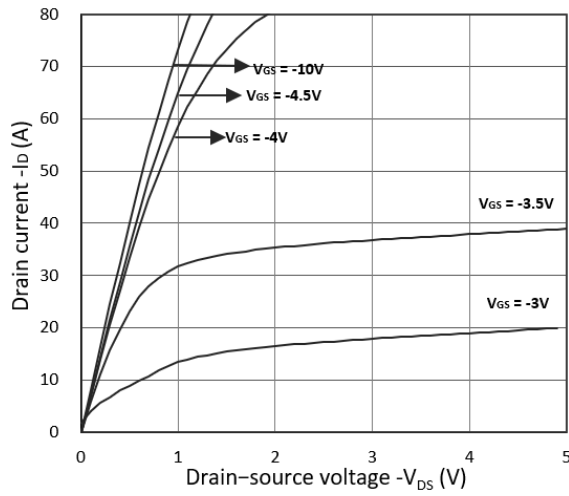


Figure 1. Output Characteristics

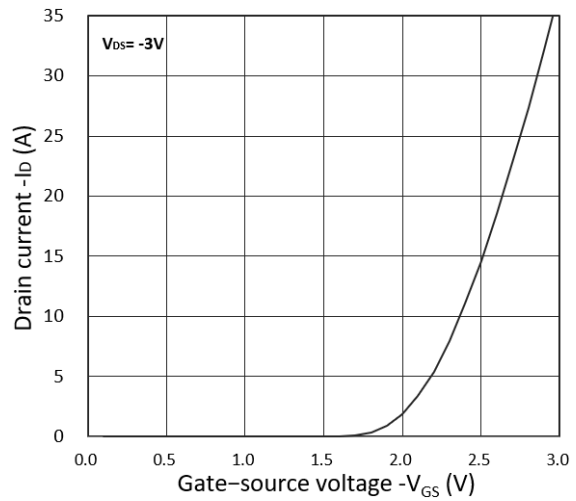


Figure 2. Transfer Characteristics

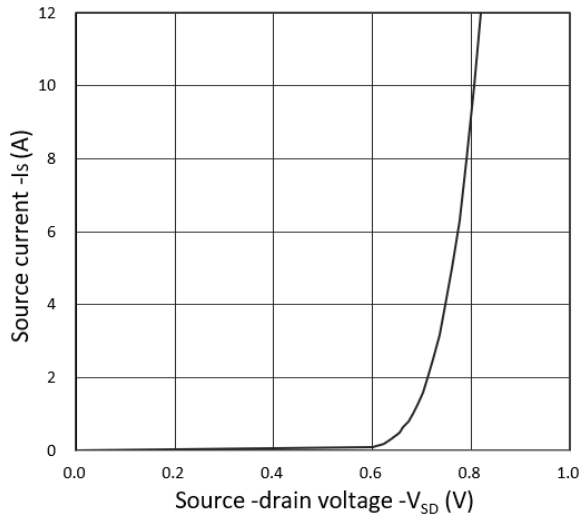


Figure 3. Forward Characteristics of Reverse

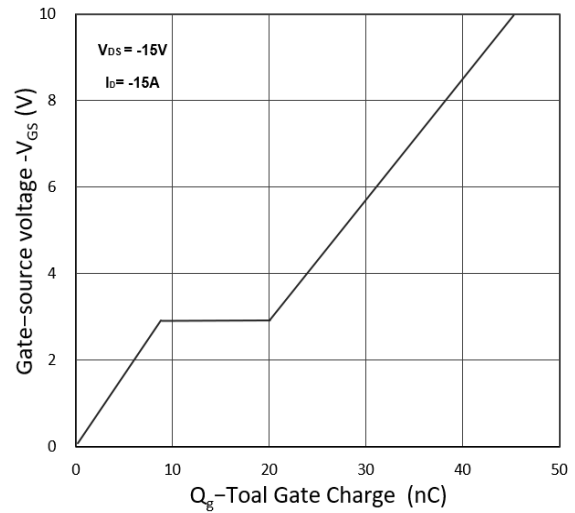


Figure 4. Gate Charge Characteristics

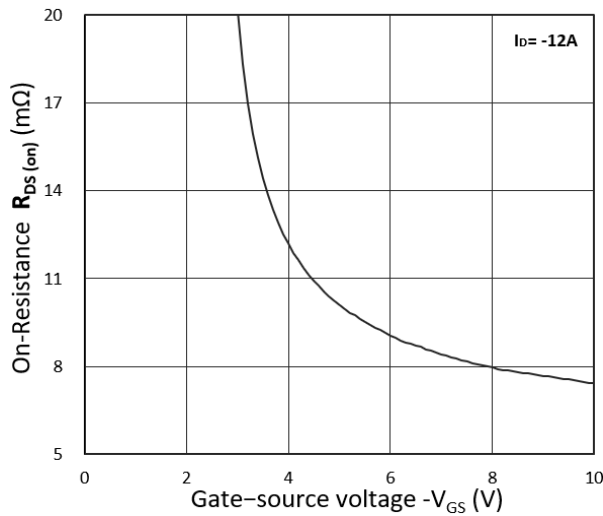


Figure 5. $R_{DS(on)}$ vs. V_{GS}

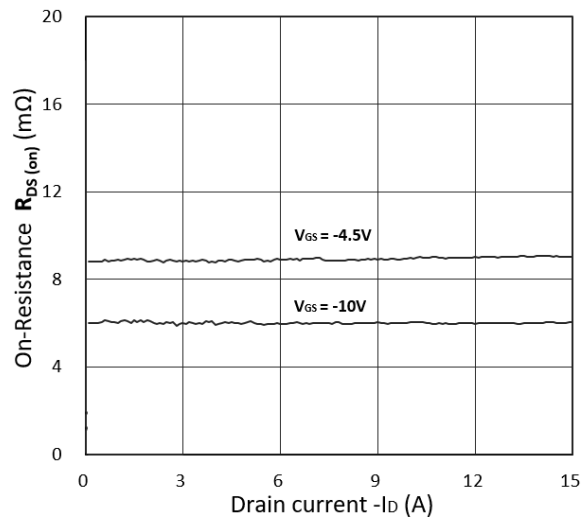


Figure 6. $R_{DS(on)}$ vs. I_D

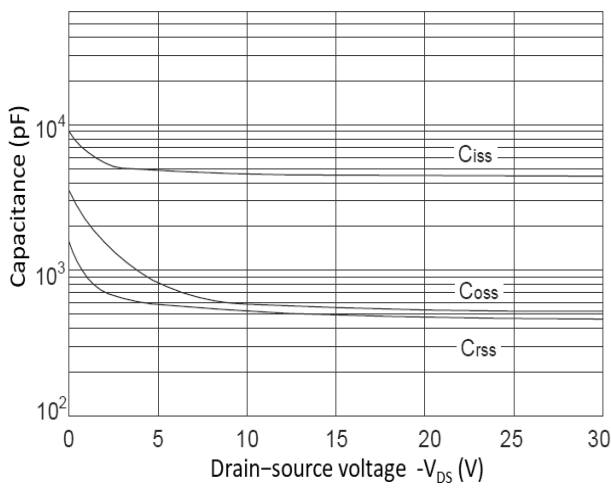


Figure 7. Capacitance Characteristics

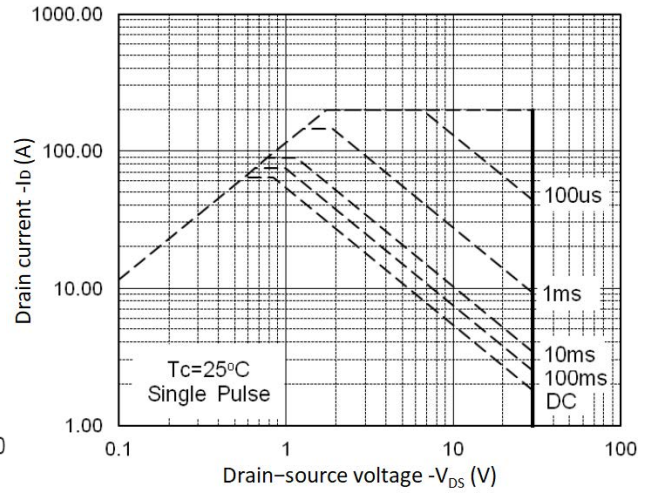


Figure 8. Safe Operating Area

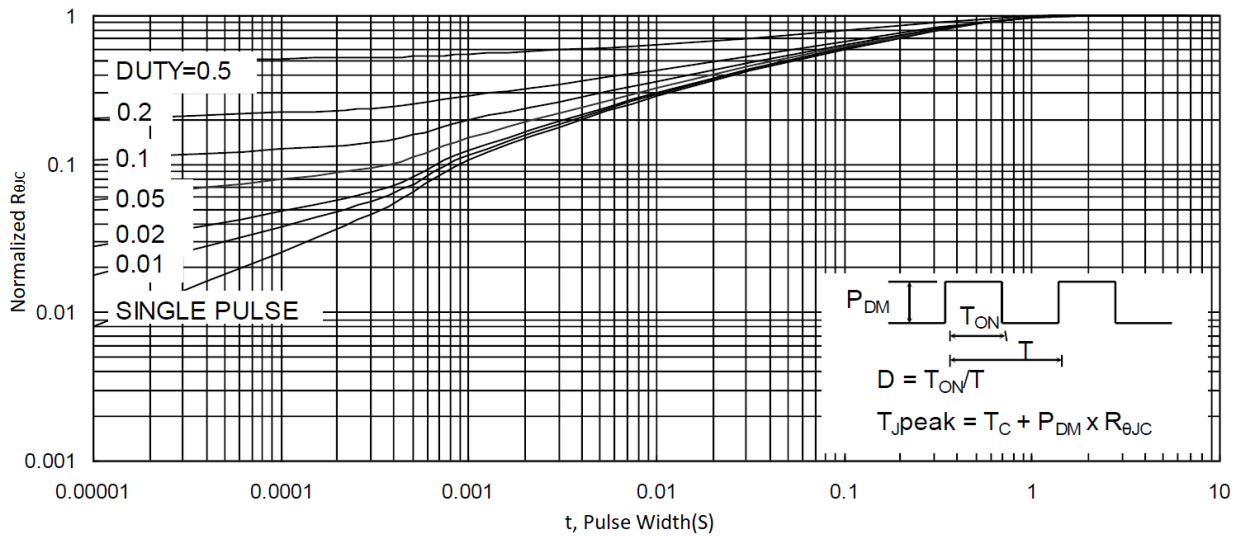


Figure 9. Normalized Maximum Transient Thermal Impedance

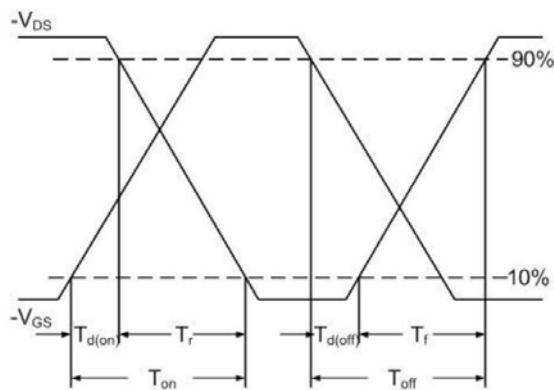


Figure 10. Switching Time Waveform

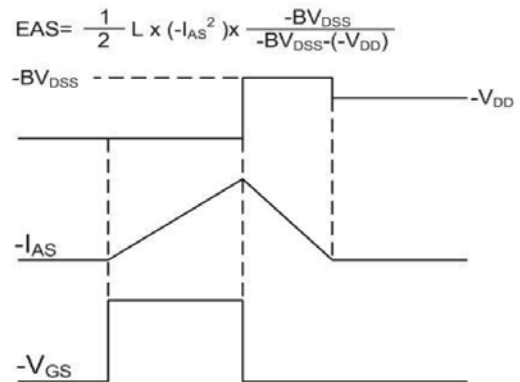
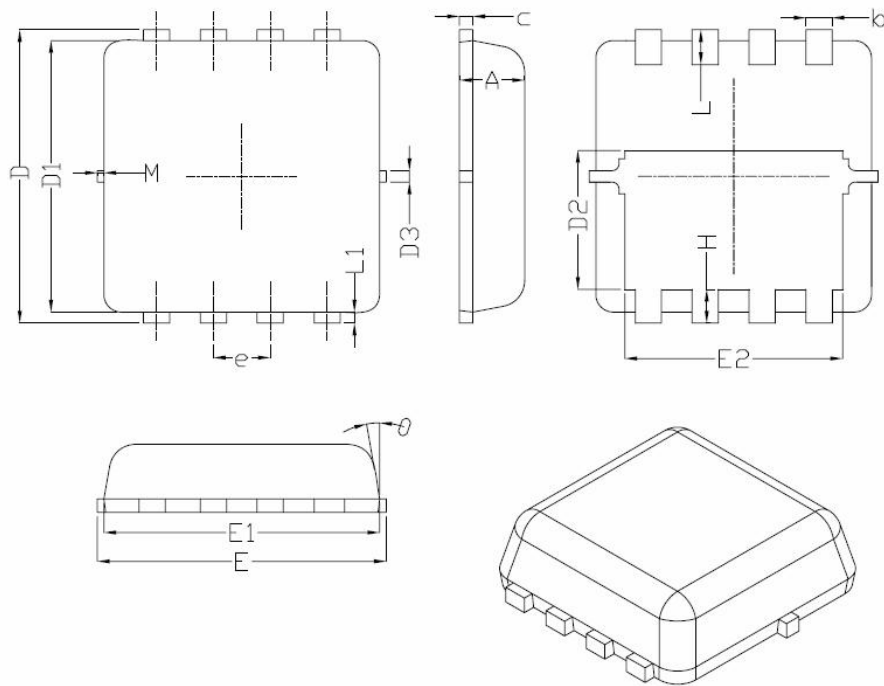


Figure 11. Unclamped Inductive Switching
Waveform

DFN3X3-8L Package Information



Symbol	Dimensions In Millimeters		
	Min.	Nom.	Max.
Ab	0.70	0.75	0.80
c	0.25	0.30	0.35
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.48	1.58	1.68
D3	-	0.13	-
E	3.20	3.30	3.40
E1E	3.00	3.15	3.20
2	2.39	2.49	2.59
e	0.65BSC		
H	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	-	0.13	-
M	*	*	0.15
θ		10°	12°

REEL SPECIFICATION

P/N	PKG	QTY
MSISH101DN-T1-GE3	DFN3X3-8L	5000

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